



DE3S062D0L

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Silicon epitaxial planar type

For ESD protection

■ Features

- High ESD
- Halogen-free / RoHS compliant
 (EU RoHS / UL-94 V-0 / MSL:Level 1 compliant)

■ Marking Symbol: 41

■ Packaging

Embossed type (Thermo-compression sealing) 3 000 pcs / reel (standard)

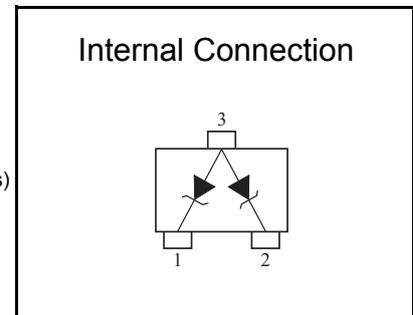
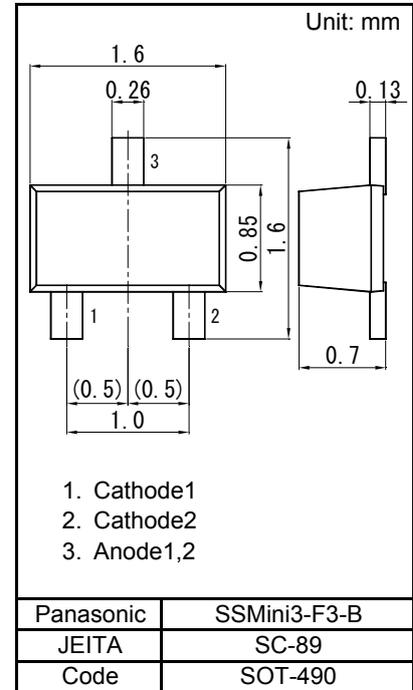
■ Absolute Maximum Ratings Ta = 25 °C

Parameter	Symbol	Rating	Unit
Total power dissipation ^{*1}	PT	150	mW
Electrostatic discharge ^{*2}	ESD	±30	kV
Junction temperature	Tj	150	°C
Operating ambient temperature	Topr	-40 to +85	°C
Storage temperature	Tstg	-55 to +150	°C

Note) *1: PT = 150 mW achieved with a printed circuit board.

(2 Diode total)

*2: Test method: IEC61000_4_2(C = 150 pF, R = 330 Ω, Contact discharge: 10 times)



■ Electrical Characteristics Ta = 25 °C ± 3 °C

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Zener voltage ^{*1, *2}	VZ	IZ = 1 mA	5.89		6.51	V
Reverse current	IR	VR = 4 V			1.0	μA
Terminal Capacitance	Ct	VR = 0 V, f = 1 MHz		55		pF
Temperature coefficient of zener voltage ^{*3}	SZ	IZ = 1 mA		2.3		mV/°C

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 Measuring methods for Diodes.

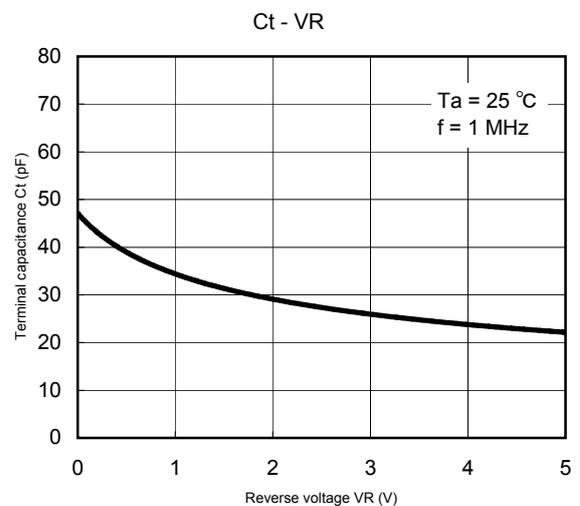
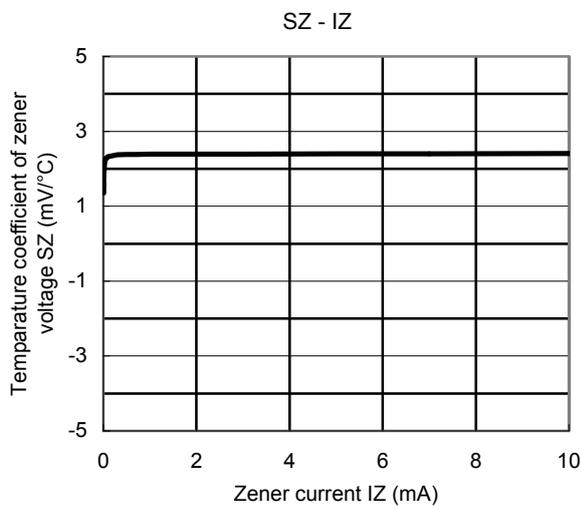
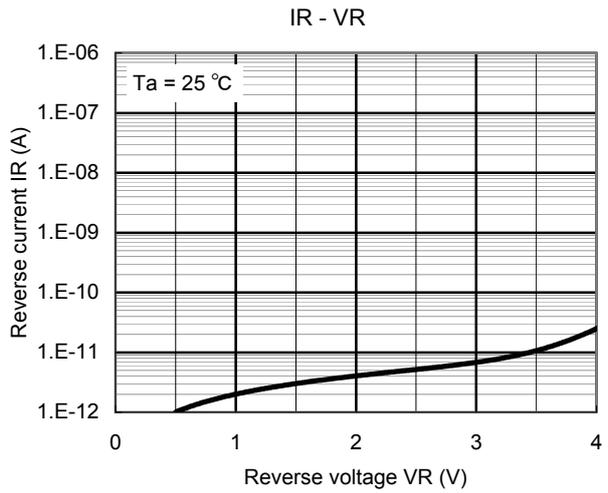
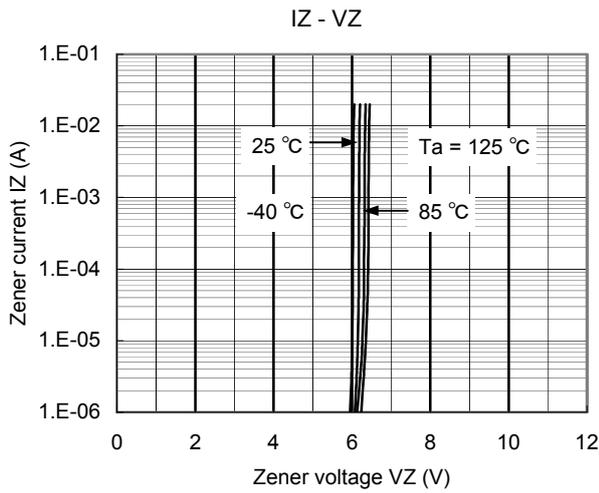
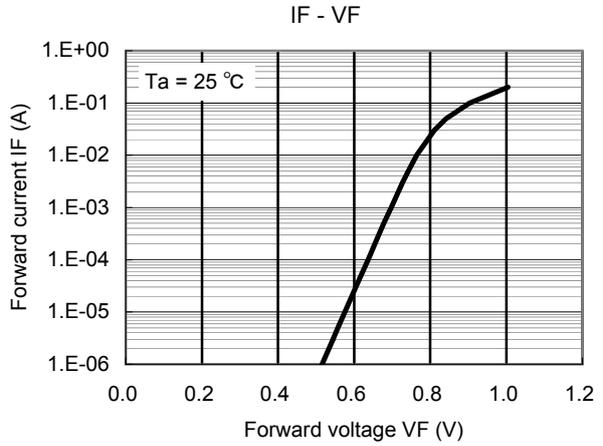
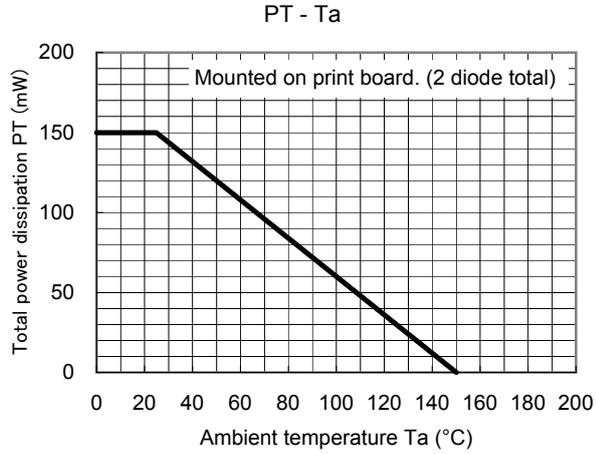
2. *1: The temperature must be controlled 25°C for VZ measurement.

VZ value measured at other temperature must be adjusted to VZ (25°C)

*2: VZ guaranteed 20 ms after current flow.

*3: Tj = 25°C to 150°C

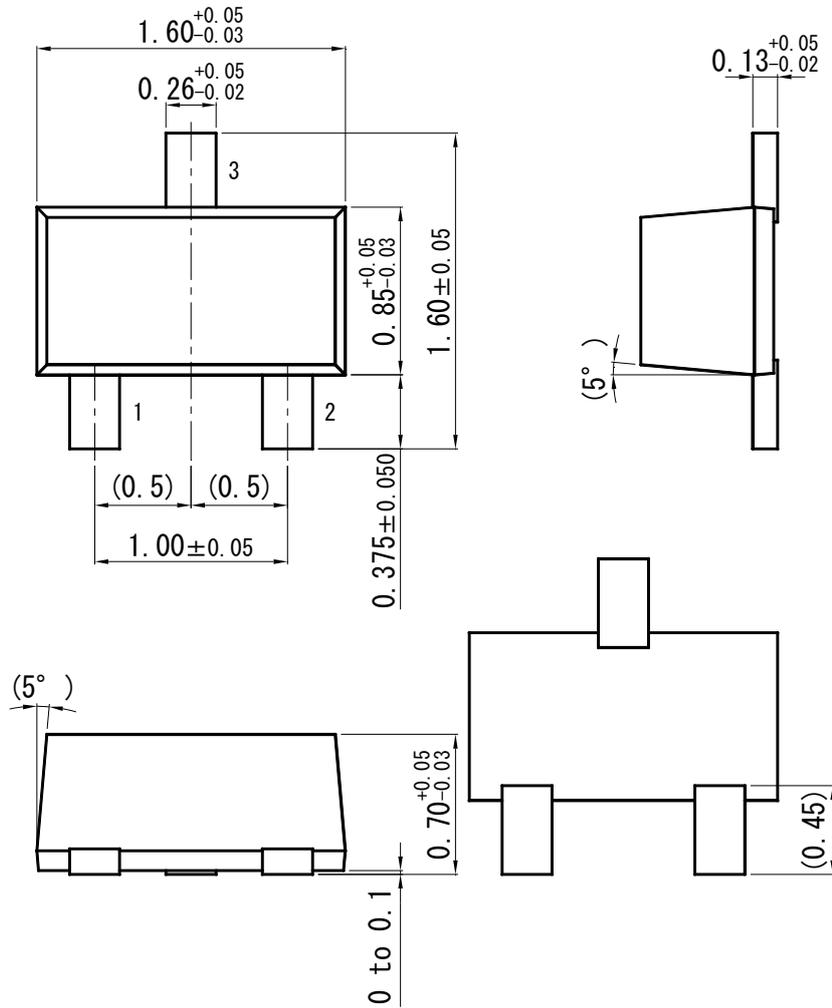
Technical Data (reference)



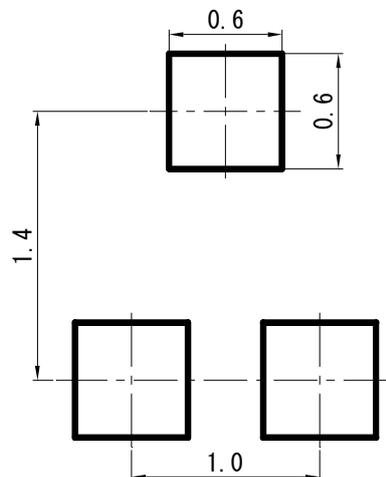


SSMini3-F3-B

Unit: mm



■ Land Pattern (Reference) (Unit: mm)



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